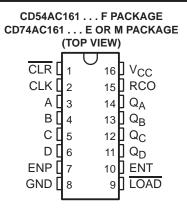
# CD54AC161, CD74AC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCHS239A - SEPTEMBER 1998 - REVISED APRIL 2000

- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2 kV ESD Protection per MIL-STD-883, Method 3015
- Package Options Include Plastic Small-Outline (M), Standard Plastic (E) and Ceramic (F) DIPs



#### description

The CD54AC161 and CD74AC161 devices are 4-bit binary counters. These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that normally are associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

These devices are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. Presetting is synchronous; therefore, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

The counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

The CD54AC161 is characterized for operation over the full military temperature range of –55°C to 125°C. The CD74AC161 is characterized for operation from –40°C to 85°C.



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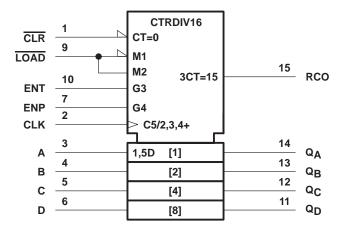
#### **FUNCTION TABLE**

		IN	IPUTS			OUTPUTS		FUNCTION
CLR	CLK	ENP	ENT	LOAD	A,B,C,D	Qn	RCO	FUNCTION
L	Χ	Χ	Χ	Χ	Χ	L	L	Reset (clear)
Н	$\uparrow$	Х	Χ	I	I	L	L	Parallel load
Н	$\uparrow$	Χ	Χ	I	h	Н	Note 1	Parallel load
Н	<b>↑</b>	h	h	h	Χ	Count	Note 1	Count
Н	Χ	I	Χ	h	Χ	q <sub>n</sub>	Note 1	Inhibit
Н	Χ	Χ	1	h	Χ	q <sub>n</sub>	L	HIHIDIC

H = high level, L = low level, X = don't care, h = high level one setup time prior to the CLK low-to-high transition, I = low level one setup time prior to the CLK low-to-high transition, q = the state of the referenced output prior to the CLK low-to-high transition,  $\uparrow$  = CLK low-to-high transition.

NOTE 1: The RCO output is high when ENT is high and the counter is at terminal count (HHHH).

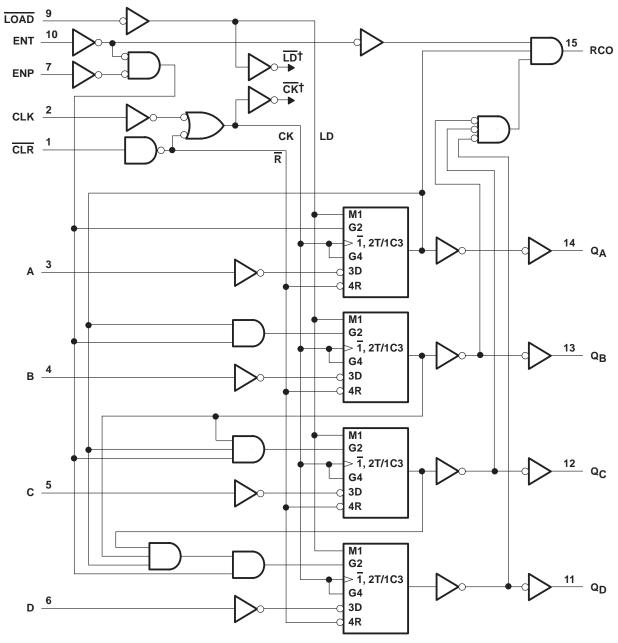
## logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

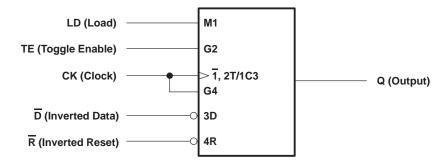


### logic diagram (positive logic)

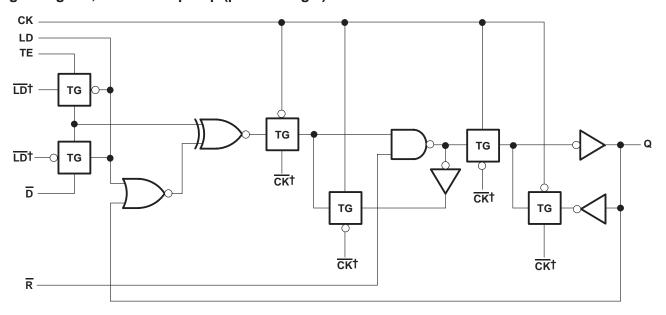


<sup>†</sup> For simplicity, routing of complementary signals  $\overline{LD}$  and  $\overline{CK}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

### logic symbol, each D/T flip-flop



### logic diagram, each D/T flip-flop (positive logic)

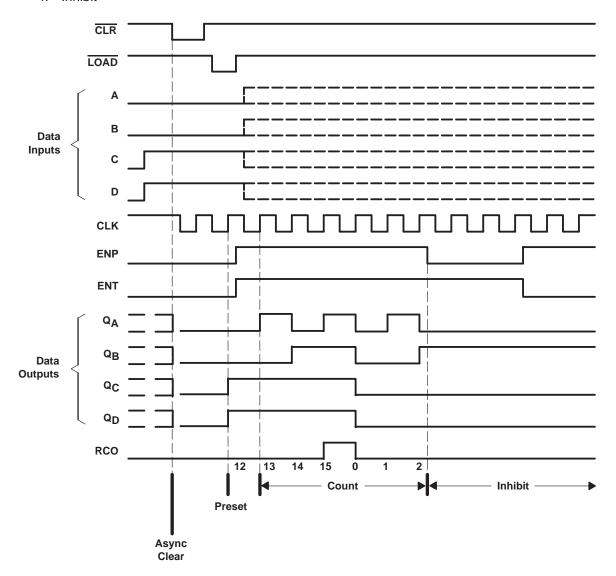


 $<sup>^{\</sup>dagger}$  The origins of  $\overline{LD}$  and  $\overline{CK}$  are shown in the logic diagram of the overall device.

### typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



### absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V <sub>CC</sub>	$-0.5\;V$ to 6 $V$
Input clamp current, $I_{IK}$ ( $V_I < 0 \text{ V or } V_I > V_{CC}$ ) (see Note 2)	$\dots \dots \pm 20 \ mA$
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 2)	$\dots \dots \pm 50 \; mA$
Continuous output current, $I_O$ ( $V_O > 0$ V or $V_O < V_{CC}$ )	$\dots \dots \pm 50 \text{ mA}$
Continuous current through V <sub>CC</sub> or GND	$\dots \dots \pm 100 \ mA$
Package thermal impedance, $\theta_{JA}$ (see Note 3): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 4)

			T <sub>A</sub> = 25°C		CD54AC161		CD74AC161		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	V
$V_{IL}$	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9		0.9	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	0	VCC	V
loh	High-level output current			-24		-24		-24	mA
loL	Low-level output current			24		24		24	mA
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V	0	50	0	50	0	50	ns
ΔυΔν	Input transition rise or fall rate	V <sub>CC</sub> = 3.6 V to 5.5 V	0	20	0	20	0	20	
TA	Operating free-air temperature				- 55	125	- 40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>3.</sup> The package thermal impedance is calculated in accordance with JESD 51.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		V	T <sub>A</sub> = 2	25°C	CD54AC161		CD74AC161		UNIT
PARAMETER	TEST COND	ITIONS	VСС	MIN	MAX	MIN	MAX	MIN	MAX	ONIT
			1.5 V	1.4		1.4		1.4		
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
Voн	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V	_		3.85		_		
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V	_		_		3.85		
	VI = VIH or VIL	Ι <sub>ΟL</sub> = 50 μΑ	1.5 V		0.1		0.1		0.1	
			3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL		I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V		_		1.65		-	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V		_		_		1.65	
lį	V <sub>I</sub> = V <sub>CC</sub> or GND		5.5 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V		8		160		80	μΑ
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

				CD54A	C161	C161 CD74AC161		UNIT
			VCC	MIN	MAX	MIN	MAX	UNII
			1.5 V		7		8	MHz
f <sub>clock</sub>	Clock frequency	3.3 V ± 0.3 V		64		73		
					90		103	
t <sub>W</sub>			1.5 V	69		61		
		CLK high or low	$3.3 \ V \pm 0.3 \ V$	7.7		6.8		
	Pulse duration		5 V ± 0.5 V	5.5		4.8		
	Pulse duration		1.5 V	63		55		ns
		CLR low	$3.3~V \pm 0.3~V$	7		6.1		
			5 V ± 0.5 V	5		4.4		
t <sub>su</sub>			1.5 V	63		55		ns
	Setup time, before CLK↑	A, B, C, or D	3.3 V ± 0.3 V	7		6.1		
			5 V ± 0.5 V	5		4.4		
			1.5 V	75		66		
		LOAD	3.3 V ± 0.3 V	8.4		7.4		
			5 V ± 0.5 V	6		5.3		
			1.5 V	0		0		
		A, B, C, or D	$3.3~V \pm 0.3~V$	0		0		ns
th	Hald far a street OLKA		5 V ± 0.5 V	0		0		
	Hold time, after CLK↑		1.5 V	0		0		
		ENP or ENT	3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		
		•	1.5 V	75		66		
t <sub>rec</sub>	Recovery time, CLR↑ before CLK↑		3.3 V ± 0.3 V	8.4		7.4		ns
			5 V ± 0.5 V	6		5.3		

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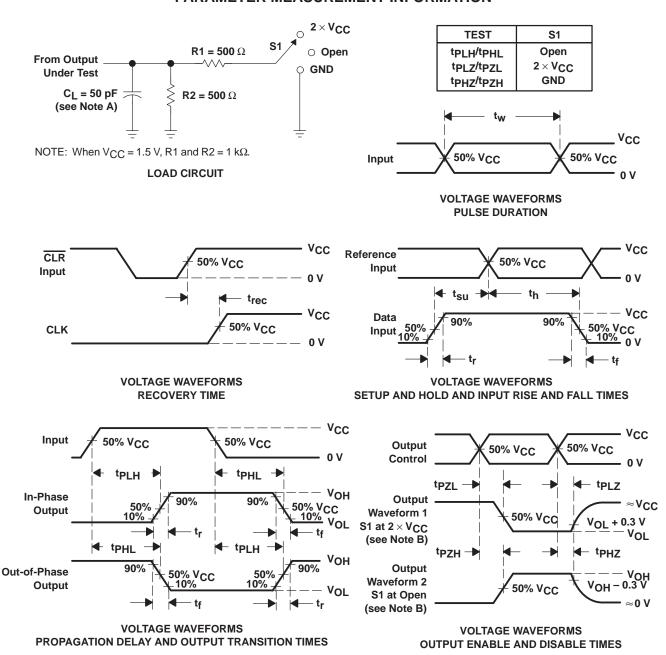
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		CD54A	C161	CD74AC161		UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	MAX	MIN	MAX	UNII
			1.5 V	7		8		
f <sub>max</sub>			3.3 V ± 0.3 V	64		73		MHz
			5 V ± 0.5 V	90		103		
			1.5 V	_	209	_	190	
		RCO	3.3 V ± 0.3 V	6	23.4	6	21	
	CLK		5 V ± 0.5 V	4.3	16.7	4.3	15.2	
	ENT	Any Q	1.5 V	_	207	_	188	
			3.3 V ± 0.3 V	5.9	23.1	5.9	21	
			5 V ± 0.5 V	4.2	16.5	4.2	15	
		RCO	1.5 V	-	129	_	117	
t <sub>pd</sub>			3.3 V ± 0.3 V	3.6	14.4	3.7	13.1	ns
			5 V ± 0.5 V	2.6	10.3	2.7	9.4	
			1.5 V	_	207	_	188	
		Any Q	3.3 V ± 0.3 V	5.9	23.1	5.9	21	
	CLR		5 V ± 0.5 V	4.2	16.5	4.2	15	
			1.5 V	_	207	_	188	
		RCO	3.3 V ± 0.3 V	5.9	23.1	5.9	21	
			5 V ± 0.5 V	4.2	16.5	4.2	15	

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	66	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3$  ns.  $t_f = 3$  ns. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpZL and tpZH are the same as ten.
- H. tpLz and tpHz are the same as tdis.

Figure 1. Load Circuit and Voltage Waveforms



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